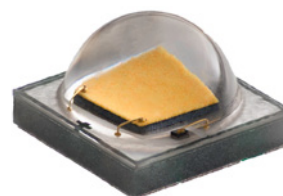


Cree® XLamp® XP Family LEDs



INTRODUCTION

This application note applies to XLamp XP Family LEDs, which have order codes in the following format.

XPxxxx-xx-xxxx-xxxxxx

This application note explains how XLamp XP Family LEDs and assemblies containing these LEDs should be handled during manufacturing. Please read the entire document to understand how to properly handle XLamp XP Family LEDs.

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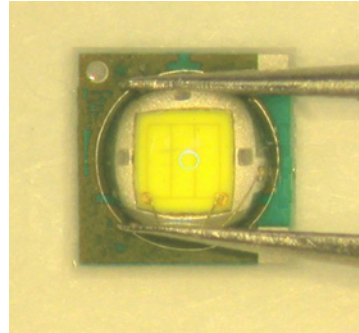
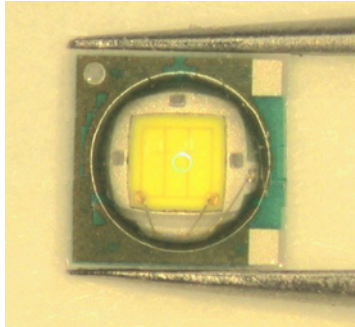
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HANDLING XLAMP XP FAMILY LEDS

Manual Handling

Use tweezers to grab XLamp XP Family LEDs at the base. Do not touch the lens with the tweezers. Do not touch the lens with fingers. Do not push on the lens.

Do not apply more than 1000 g of shear force directly onto the lens. Excessive force on the lens could damage the LED.



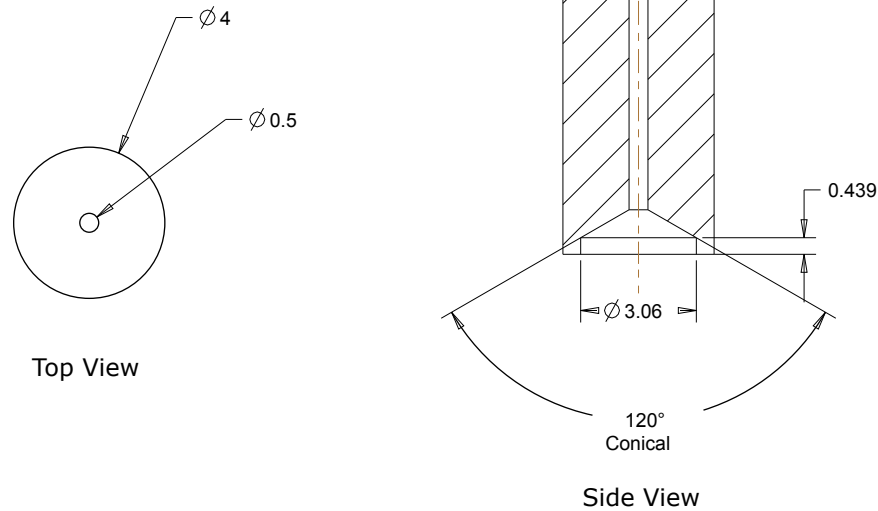
Cree recommends the following at all times when handling XLamp XP Family LEDs or assemblies containing these LEDs:

- Avoid putting mechanical stress on the LED lens.
- Never touch the optical surface with fingers or sharp objects. The LED lens surface could be soiled or damaged, which would affect the optical performance of the LED.

The following diagram shows an example of a pick & place tool to remove XLamp XP-C, XP-E and XP-G LEDs from the factory tape & reel packaging.

All dimensions in mm

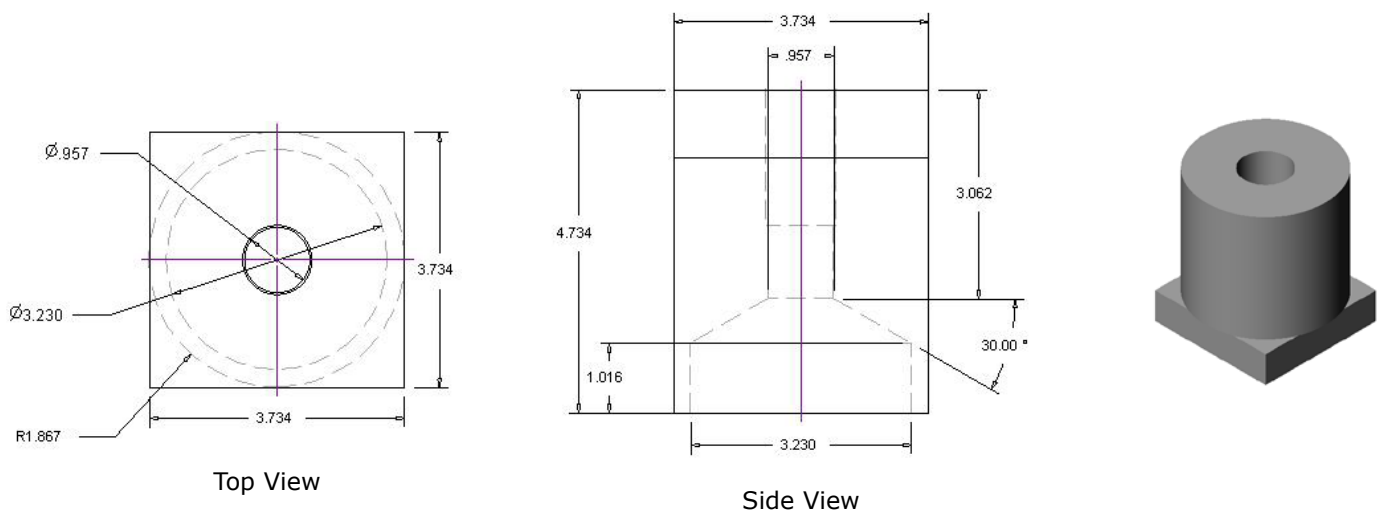
Tolerance: + 0.01



The following diagram shows an example of a pick & place tool to remove XLamp XP-E2 and XP-G2 LEDs from the factory tape & reel packaging. The nozzle is implemented in urethane.

All dimensions in mm

Tolerance: ± 0.01

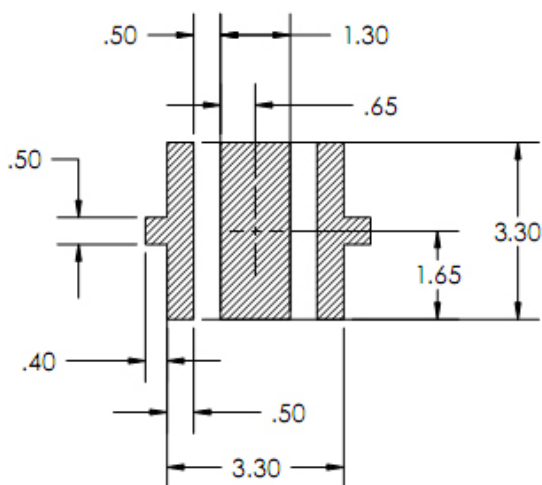


CIRCUIT BOARD PREPARATION & LAYOUTS

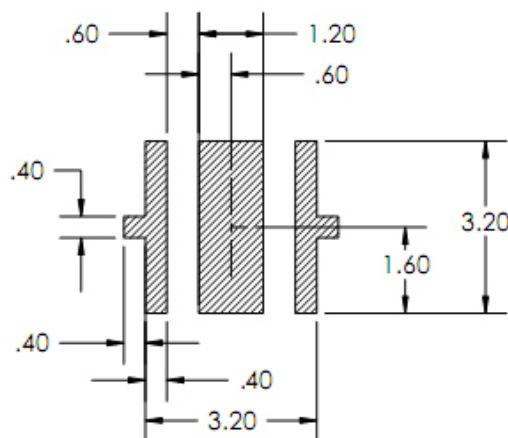
Printed circuit boards (PCBs) should be prepared and/or cleaned according to the manufacturer's specifications before placing or soldering XLamp XP Family LEDs onto the PCB.

The diagram below shows the recommended PCB solder pad layout for XLamp XP Family LEDs.

All dimensions in mm



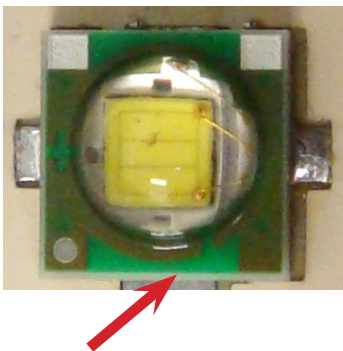
Recommended PCB Solder Pad



Recommended Stencil Pattern
(hatched area is opening)

CASE TEMPERATURE (T_s) MEASUREMENT POINT

XLamp XP Family LED case temperature (T_s) should be measured on the PCB surface, as close to the LED's thermal pad as possible. This measurement point is shown in the picture below.



It is not required to use a solder footprint for the thermal pad that is larger than the XLamp XP Family LED itself. In testing, Cree has found such a solder pad to have insignificant impact on the resulting T_s measurement.

NOTES ON SOLDERING XLAMP XP FAMILY LEDs

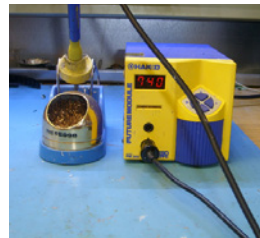
XLamp XP Family LEDs are designed to be reflow soldered to a PCB. Reflow soldering may be done by a reflow oven or by placing the PCB on a hotplate and following the reflow soldering profile listed on the previous page.

Do not wave solder XLamp XP Family LEDs. Do not hand solder XLamp XP Family LEDs.

✓
CORRECT



✓
CORRECT



Solder Paste Type

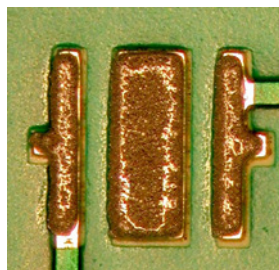
Cree strongly recommends using “no clean” solder paste with XLamp XP Family LEDs so that cleaning the PCB after soldering is not required. Cree uses Kester r276 solder paste internally.¹

Cree recommends the following solder paste compositions: SnAgCu (tin/silver/copper) and SnAg (tin/silver).

Solder Paste Thickness

The choice of solder and the application method will dictate the specific amount of solder. For the most consistent results, an automated dispensing system or a solder stencil printer is recommended. Cree has seen positive results using solder thickness that results in a 3-mil (75-μm) bond line, i.e., the solder joint thickness after reflow soldering.

✓
CORRECT



✗
WRONG

¹ kester.com/Portals/0/documents/Electronic-Assembly-Materials.pdf

NOTES ON SOLDERING XLAMP XP FAMILY LEDS (CONTINUED)

After Soldering

After soldering, allow XLamp XP Family LEDs to return to room temperature before subsequent handling. Premature handling of the device, especially around the lens, could result in damage to the LED.

Cree recommends verifying the solder process by checking the consistency of the solder bond of several trial PCBs after reflow. After shearing selected devices from the circuit board the solder should appear completely re-flowed (no solder grains evident). The solder areas should show minimum evidence of voids on the backside of the package and the PCB.

Cleaning PCBs After Soldering

Cree recommends using “no clean” solder paste so that flux cleaning is not necessary after reflow soldering. If PCB cleaning is necessary, Cree recommends the use of isopropyl alcohol (IPA).

Do not use ultrasonic cleaning.

MOISTURE SENSITIVITY

In testing, Cree has found XLamp XP Family LEDs to have unlimited floor life in conditions $\leq 30^{\circ}\text{C}$ / 85% relative humidity (RH). Moisture testing included a 168 -hour soak at 85°C / 85% RH followed by 3 reflow cycles, with visual and electrical inspections at each stage.

Cree recommends keeping XLamp LEDs in their sealed moisture-barrier packaging until immediately prior to use. Cree also recommends returning any unused LEDS to the resealable moisture-barrier bag and closing the bag immediately after use.

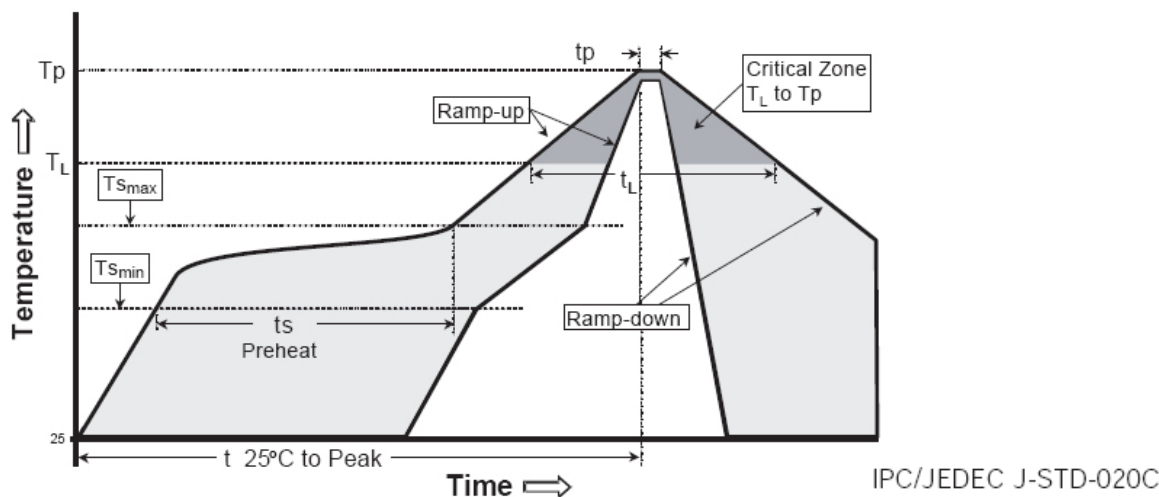
LOW TEMPERATURE OPERATION

The minimum operating temperature of these XLamp components is -40°C . To maximize lifetime, Cree recommends avoiding applications where the lamps are cycled on and off more than 10,000 cycles at temperatures below 0°C .

XLAMP XP FAMILY LED REFLOW SOLDERING CHARACTERISTICS

In testing, Cree has found XLamp XP Family LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree recommends that users follow the recommended soldering profile provided by the manufacturer of solder paste used.

Note that this general guideline may not apply to all PCB designs and configurations of reflow soldering equipment.



Profile Feature	Lead-Based Solder	Lead-Free Solder
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3°C/second max.	3°C/second max.
Preheat: Temperature Min ($T_{s_{min}}$)	100 °C	150 °C
Preheat: Temperature Max ($T_{s_{max}}$)	150 °C	200 °C
Preheat: Time ($t_{s_{min}}$ to $t_{s_{max}}$)	60-120 seconds	60-180 seconds
Time Maintained Above: Temperature (T_L)	183 °C	217 °C
Time Maintained Above: Time (t_L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature (T_p)	215 °C	260 °C
Time Within 5°C of Actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

CHEMICALS & CONFORMAL COATINGS

Below are representative lists of chemicals and materials to be used or avoided in LED manufacturing activities. For a complete and current list of recommended chemicals, conformal coatings and harmful chemicals consult Cree's Chemical Compatibility Application Note.² The video at www.youtube.com/watch?v=t24bf9D_1SA illustrates the process Cree has developed for testing the compatibility of chemicals and materials with LEDs. You should also consult your regional Cree Field Applications Engineer.

Recommended Chemicals

In testing, Cree has found the following chemicals to be safe to use with XLamp XP family LEDs.

- Water
- Isopropyl alcohol (IPA)

Chemicals Tested as Harmful

In general, subject to the specifics in Cree's Chemical Compatibility Application Note, Cree has found certain chemicals to be harmful to XLamp XP family LEDs. Cree recommends not using these chemicals anywhere in an LED system containing XLamp XP family LEDs. The fumes from even small amounts of the chemicals may damage the LEDs.

- Chemicals that might outgas aromatic hydrocarbons (e.g., toluene, benzene, xylene)
- Methyl acetate or ethyl acetate (i.e., nail polish remover)
- Cyanoacrylates (i.e., "Superglue")
- Glycol ethers (including Radio Shack® Precision Electronics Cleaner - dipropylene glycol monomethyl ether)
- Formaldehyde or butadiene (including Ashland PLIOBOND® adhesive)

² Chemical Compatibility Application Note, AP63, www.cree.com/xlamp_app_notes/chemical_compatibility

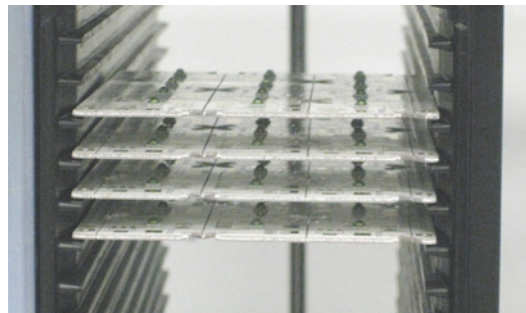
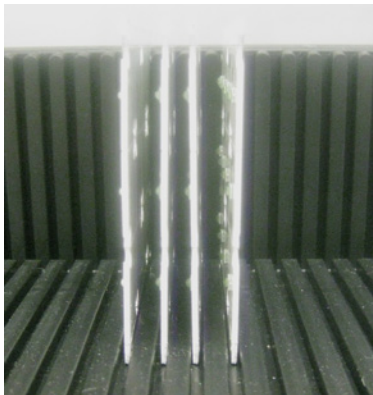
ASSEMBLY STORAGE & HANDLING

Do not stack PCBs or assemblies containing XLamp XP Family LEDs so that anything rests on the LED lens. Force applied to the LED lens may result in the lens being knocked off. PCBs or assemblies containing XLamp XP Family LEDs should be stacked in a way to allow at least 2-cm clearance above the LED lens.

Do not use bubble wrap directly on top of XLamp XP Family LEDs. Force from the bubble wrap can potentially damage the LED.



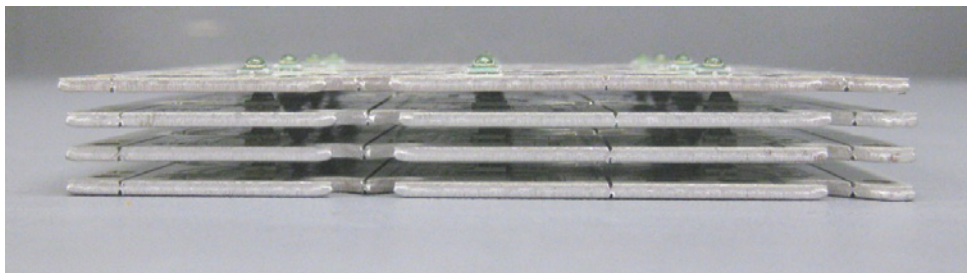
CORRECT



CORRECT



WRONG

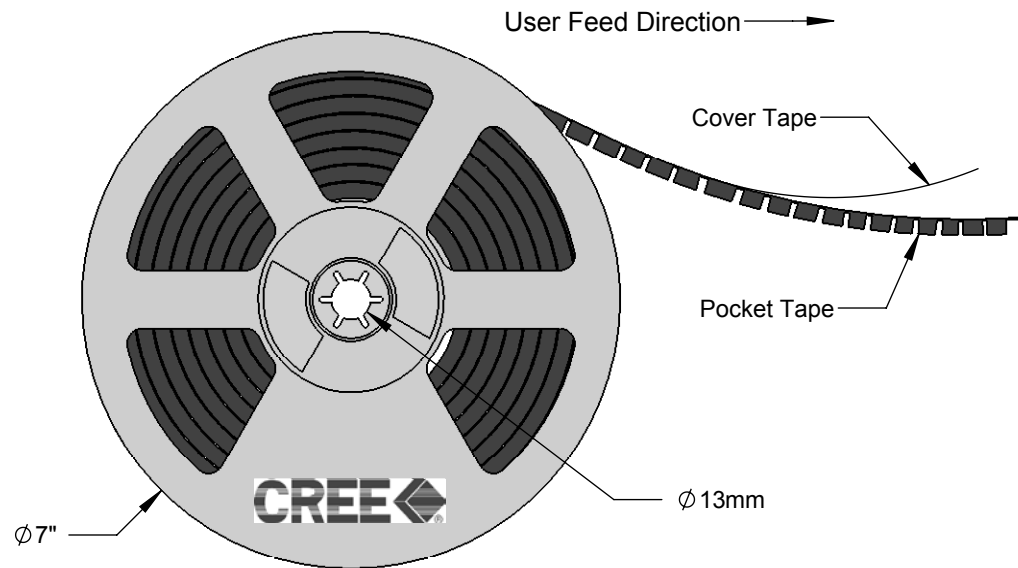


TAPE AND REEL

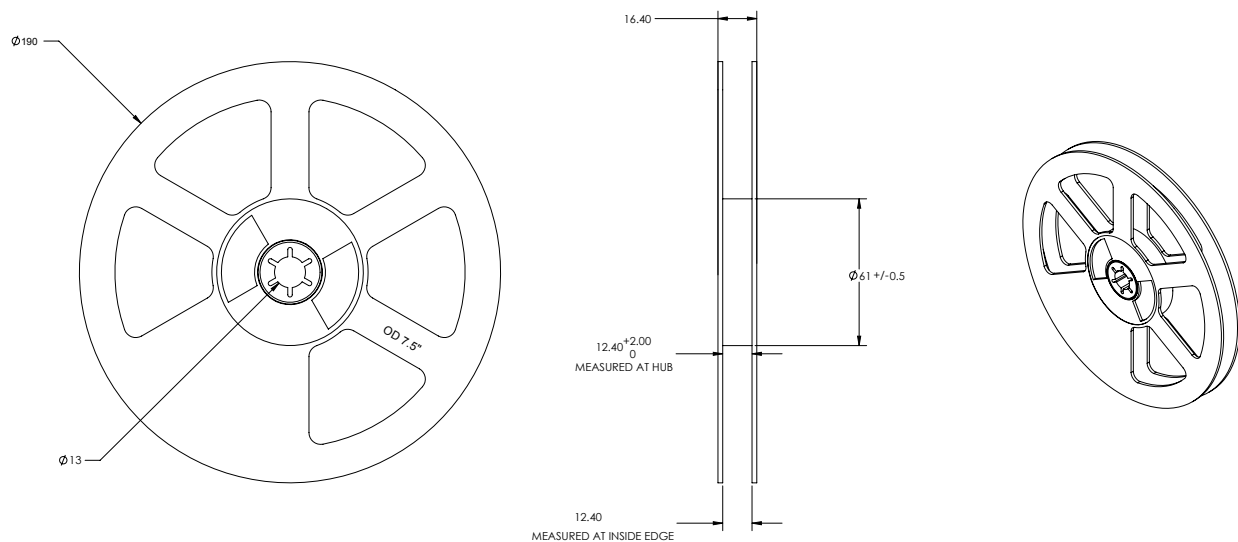
All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.

All dimensions in mm.

XP-C, XP-E, XP-G

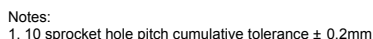


XP-E2, XP-G2



All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.

XP-C, XP-E, XP-G



SECTION Y-Y

SECTION X-X

3D PERSPECTIVE VIEW

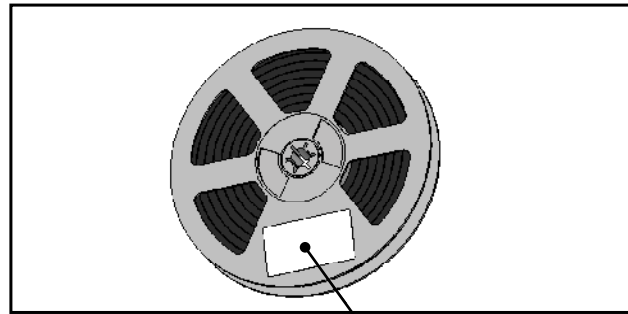
Ao	3.70	+/- 0.1
Bo	3.70	+/- 0.1
Ko	2.40	+0.0/-0.1
F	5.50	+/- 0.05
P ₁	8.00	+/- 0.1
W	12.00	+0.3/-0.1

(I) Measured from centerline of sprocket hole to centerline of pocket.
 (II) Cumulative tolerance of 10 sprocket holes is ± 0.20 .
 (III) Measured from centerline of sprocket hole to centerline of pocket.
 (IV) Other material available.

PACKAGING & LABELS

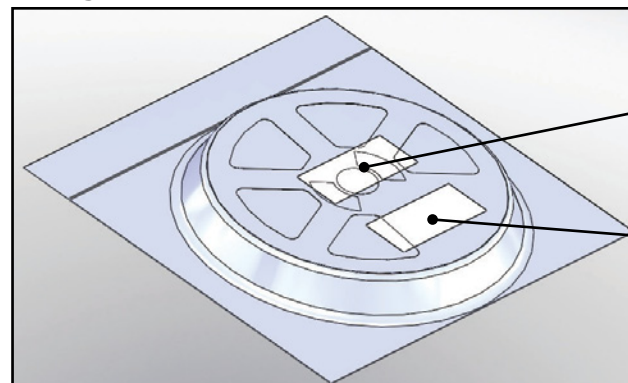
The diagrams below show the packaging and labels Cree uses to ship XLamp XP Family LEDs. XLamp XP Family LEDs are shipped in tape loaded on a reel. Each box contains only one reel in a moisture barrier bag.

Unpackaged Reel



Label with Cree Bin Code, Qty, Reel ID

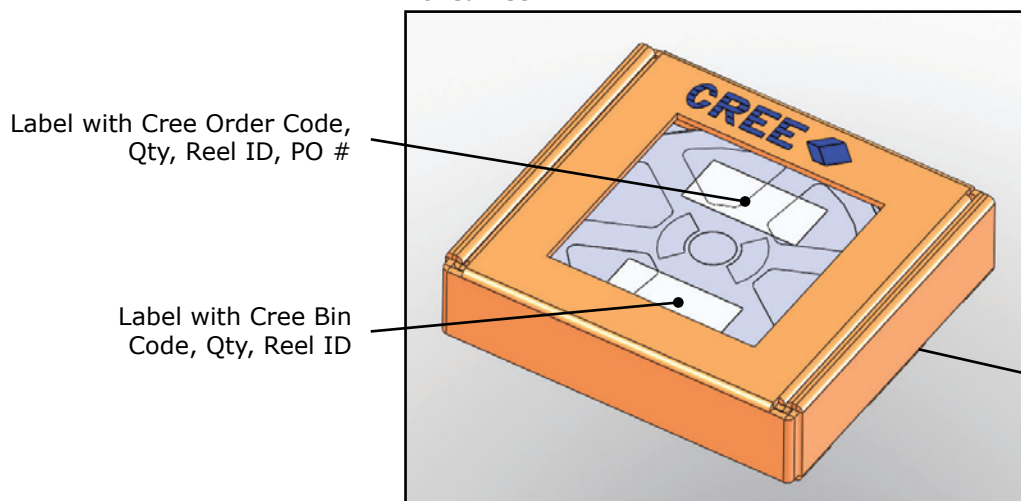
Packaged Reel



Label with Cree Order Code, Qty, Reel ID, PO #

Label with Cree Bin Code, Qty, Reel ID

Boxed Reel



Label with Cree Order Code, Qty, Reel ID, PO #

Label with Cree Bin Code, Qty, Reel ID

Patent Label (on bottom of box)